



SLOVENSKI STANDARD
oSIST prEN IEC 62680-1-2:2022

01-marec-2022

**Vmesniki univerzalnega serijskega vodila za prenos podatkov in napajanje - 1-2.
del: Skupne komponente - Specifikacija za zagotavljanje napajanja prek USB**

Universal serial bus interfaces for data and power - Part 1-2: Common components -
USB Power Delivery specification

Schnittstellen des Universellen Seriellen Busses für Daten und Energie - Teil 1-2:
Gemeinsame Komponenten - Festlegung für die USB-Stromversorgung

Interfaces de bus universel en série pour les données et l'alimentation électrique - Partie
1-2: Composants communs - Spécification de l'alimentation électrique par port USB

Ta slovenski standard je istoveten z: prEN IEC 62680-1-2:2022

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ICS:

35.200	Vmesniška in povezovalna oprema	Interface and interconnection equipment
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SUPERSEDES DOCUMENTS:

100/3708/RR

IEC TA 18 : MULTIMEDIA HOME SYSTEMS AND APPLICATIONS FOR END-USER NETWORKS	
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TITLE:

Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification

PROPOSED STABILITY DATE: 2026

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UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER**Part 1-2: Common components – USB Power Delivery specification**

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FDIS	Report on voting
XX/XX/FDIS	XX/XX/RVD

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This standard is the USB-IF publication Universal Serial Bus Power Delivery Specification Revision 3.1, Version 1.1.

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Universal Serial Bus Power Delivery Specification

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Version: **1.1** [oSIST prEN IEC 62680-1-2:2022
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Pat Crowe	MQP Electronics Ltd.	Narendra Mehta	Qualcomm, Inc.
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Pekka Leinonen	Nokia Corporation	Tsung-Peng Chuang	Realtek Semiconductor Corp.
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Sten Carlsen	Nokia Corporation	Bob Dunstan	Renesas Electronics Corp.
Abhijeet Kulkarni	NXP Semiconductors	Brian Allen	Renesas Electronics Corp.
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Dennis Ha	NXP Semiconductors	John Carpenter	Renesas Electronics Corp.
Dong Nguyen	NXP Semiconductors	Kiichi Muto	Renesas Electronics Corp.
Guru Prasad	NXP Semiconductors	Masami Katagiri	Renesas Electronics Corp.
Ken Jaramillo	NXP Semiconductors	Nobuo Furuya	Renesas Electronics Corp.
Krishnan TN	NXP Semiconductors	Patrick Yu	Renesas Electronics Corp.
Michael Joehren	NXP Semiconductors	Peter Teng	Renesas Electronics Corp.
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Rod Whitby	NXP Semiconductors	Steve Roux	Renesas Electronics Corp.
Vijendra Kuroodi	NXP Semiconductors	Tetsu Sato	Renesas Electronics Corp.
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Andrew Yoo	ON Semiconductor	Heinz Wei	Richtek Technology Corporation
Brady Maasen	ON Semiconductor	TZUHSIEN CHUANG	Richtek Technology Corporation
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Christian Klein	ON Semiconductor	Akihiro Ono	Rohm Co. Ltd.
Cor Voorwinden	ON Semiconductor	Chris Lin	Rohm Co. Ltd.
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Michael Smith	ON Semiconductor	Kris Bahar	Rohm Co. Ltd.
Oscar Freitas	ON Semiconductor	Manabu Miyata	Rohm Co. Ltd.
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Craig Wiley	Parade Technologies Inc.	Vijendra Kuroodi	Rohm Co. Ltd.
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Amruta Patra	Power Integrations	Matti Kulmala	Salcomp Plc
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Kafai Leung	Silicon Laboratories, Inc.	Nivin George	Synopsys, Inc.
Kok Hong Soh	Silicon Laboratories, Inc.	Zongyao Wen	Synopsys, Inc.
Sorin Badiu	Silicon Laboratories, Inc.	Joan Marrinan	Tektronix
Steven Ghang	Silicon Laboratories, Inc.	Kimberley McKay	Teledyne-LeCroy
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Aniket Mathad	SiliConch Systems Private Limited	Tony Minchell	Teledyne-LeCroy
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Jinisha Patel	SiliConch Systems Private Limited	Bing Lu	Texas Instruments
Kaustubh Kumar	SiliConch Systems Private Limited	Deric Waters	Texas Instruments
Nitish	SiliConch Systems Private Limited	Grant Ley	Texas Instruments
Pavitra	SiliConch Systems Private Limited	Gregory Watkins	Texas Instruments
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Patrizia Milazzo	ST-Ericsson	Jay Tseng	VIA Technologies, Inc.
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